# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

| HP x2 210 G2 Detachable PC |

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>1</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble the slate & docking ass’y
2. Remove battery cable from connecter on MB
3. Disassemble bezel ass’y from A-cover ass’y
4. Remove LCD cable with touch glass control board
5. Release antenna cu-foil
6. Release Thermal shielding screw*8 pcs
7. Release battery screw *1 pcs
8. Remove battery pack
9. Release SPK R screw *1 pcs
10. Remove speaker R
11. Release slate pogo connecter screw *2 pcs
12. Release pogo cable connecter on MB
13. Remove the pogo cable & RTC battery
14. Release antenna connecter *2
15. Release power & audio & volume ffc connecter on MB
16. Release camera cable connecter on MB
17. Remove speaker L
18. Release MB screw *1 pcs
19. Release rear camera bracket and rear camera
20. Remove Mother Board
21. Remove rear camera
22. Remove rear camera bracket
23. Release type-C bracket screw *2 pcs
24. Remove type-C bracket
25. Release audio board bracket screw *1 pcs
26. Remove audio bracket
27. Release ffc connecter on audio board
28. Remove audio bord
29. Remove audio ffc
30. Release volume board screw *2 pcs
31. Release ffc connecter on volume board
32. Remove volume bord
33. Remove volume ffc
34. Release power board screw *1 pcs
35. Release ffc connecter on power board

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36. Remove power bord  
37. Remove power ffc  
38. Release camera cable connecter on camera module  
39. Remove camera cable  
40. Remove camera module  
41. Remove base rubber  
42. Release base screw *4 pcs  
43. Remove base mylar *2 pcs  
44. Release base screw *2 pcs  
45. Disassemble the base cover from docking ass'y  
46. Release docking pogo cable connecter from docking DB  
47. Release the KB membrane from docking DB  
48. Release ffc connecter on docking DB & TP module  
49. Remove TP module ffc  
50. Release docking DB screw *1 pcs  
51. Remove docking DB  
52. Release TP support bracket screw *3 pcs  
53. Remove TP support bracket  
54. Remove KB membrane mylar  
55. Release TP holder screw *3 pcs  
56. Remove TP ass'y  
57. Remove TP mylar  
58. Remove TP module  
59. Release hinge bracket L&R screw *4 pcs  
60. Disassemble the hinge bar ass'y from top ass'y  
61. Remove hinge bar Mylar  
62. Release hinge bar bezel screw *3 pcs  
63. Disassemble the hinge bar bezel from hinge bar cover ass'y  
64. Release docking pogo cable connecter screw *1 pcs  
65. Remove docking pogo cable  
66. Release hinge L&R screw *2 pcs  
67. Remove hinge L&R from hinge bar cover ass'y  
68. END

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly
3.22 Remove battery module

3.23 Remove service door

3.24 LCD module set disassembly

3.25 Top case disassembly

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
3.26 Thermal module and mother board disassembly

3.27 Bottom case disassembly